A method and apparatus for uniformly spin-coating photoresist material on wafers before the wafers are subjected to a photoetching process. The spin-coating apparatus comprises a first rotating device for rotating a rotating connector about a first axis and a second rotating device located on the outer portion of the rotating connector. The second rotating device rotates a wafer about a second axis while the rotating connector rotates around the first axis. The first and second axes are parallel to each other but are spaced apart by a designated distance. The designated distance can be adjusted and a plurality of second rotating devices may be connected to outer portions of the rotating connector.